



TotalEnergies

Refining & Chemicals
Polymers

Polyethylene HDPE 56020 SXP

Technical data sheet
High Density Polyethylene BLOW MOULDING
Produced in Europe

Description

HDPE 56020 SXP is a very high molecular weight (VHMW) high density polyethylene (HDPE) with high resistance to impact, good chemical resistance and optimized balance between Environmental Stress Cracking Resistance (ESCR) and rigidity. It has been specifically designed for the manufacture of blow molded UN-marked articles (tight head drums, open top drums and jerry-cans) dedicated for the transportation of dangerous goods.

HDPE 56020 SXP is a pellet grade and contains antioxidants.

Characteristics

Property	Method	Unit	Typical value (*)
Density	ISO 1183	g/cm ³	0.952
Melt Flow Rate (190°C/21.6 kg)	ISO 1133/G	g/10 min	1.4
ESCR AntaroX 100%	ASTM D 1693B	h	F ₅₀ > 250
Notched Charpy Impact Resistance 23°C	ISO 179-1	kJ/m ²	80
Notched Charpy Impact Resistance -30°C	ISO 179-1	kJ/m ²	55

(*) Data not intended for specification purposes

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

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